

Process Flow Chart for 1 + 4 + 1 design ;

(L3-L4)

1. Board Cutting
2. I/L Dry Film
3. I/L Develop, Etch & Strip
4. AOI
5. I/L Brown Oxide
6. Lay-Up
7. Lamination
8. X-Ray Drilling, (1st set target hole)

↓ (L2-L5)

9. Buried Hole Drilling [TP1(L2-L5)]
10. Desmear, PTH & Panel Plating
11. Via Hole Plugged
12. Surface dressing
13. I/L Dry Film
14. I/L Develop, Etch & Strip
15. AOI
16. I/L Brown Oxide
17. Lay-Up
18. Lamination
19. X-Ray Drilling [TP2(L1-L6)]

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(L1-L6)

20. Conformal Mask Imaging
21. Conformal Mask Develop, Etch & Strip
22. Laser Drilling [TP3(L1-L2) & TP4(L5-L6)]
23. Through Hole Drilling [TP2 (L1-L6)]
24. Desmear, PTH & Panel Plating
25. O/L Dry Film (Layer 1, layer 6)
26. Pattern Plating
27. O/L Etch & Stripping
28. Outer AOI
29. S/M (Plug Hole & Surface Coating)
30. Component Mark
31. Immersion Gold
32. Routing (Profiling)
33. Electrical Test
34. Final Inspection, & Outgoing QA
35. Packing

